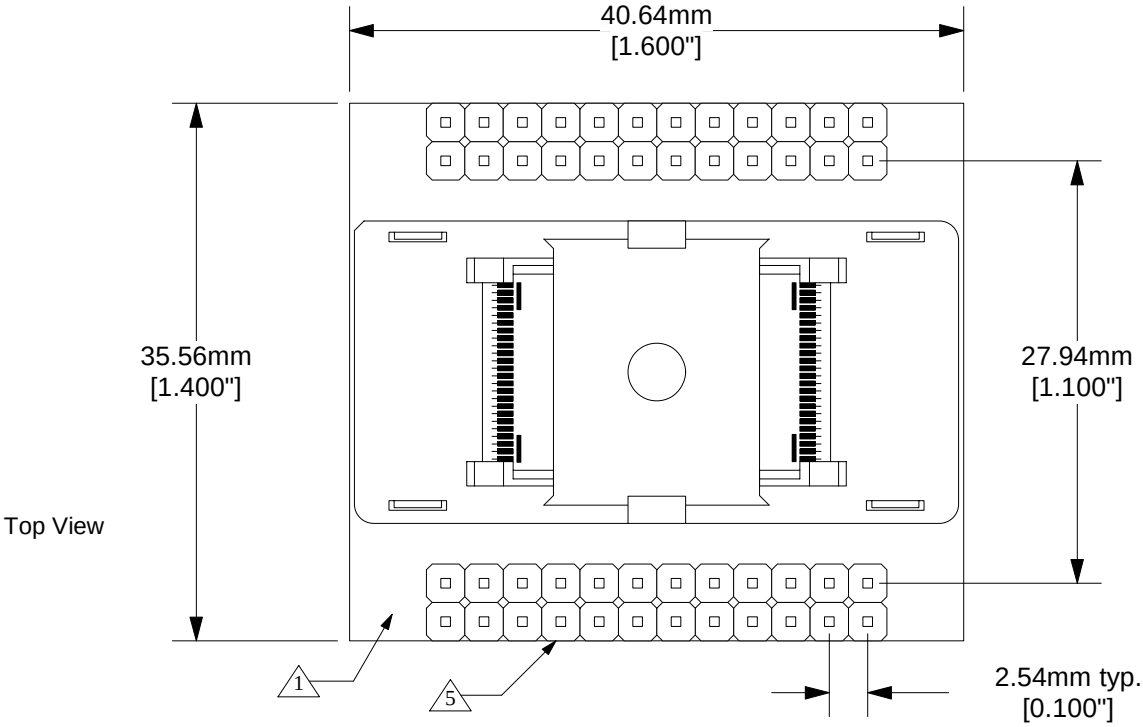


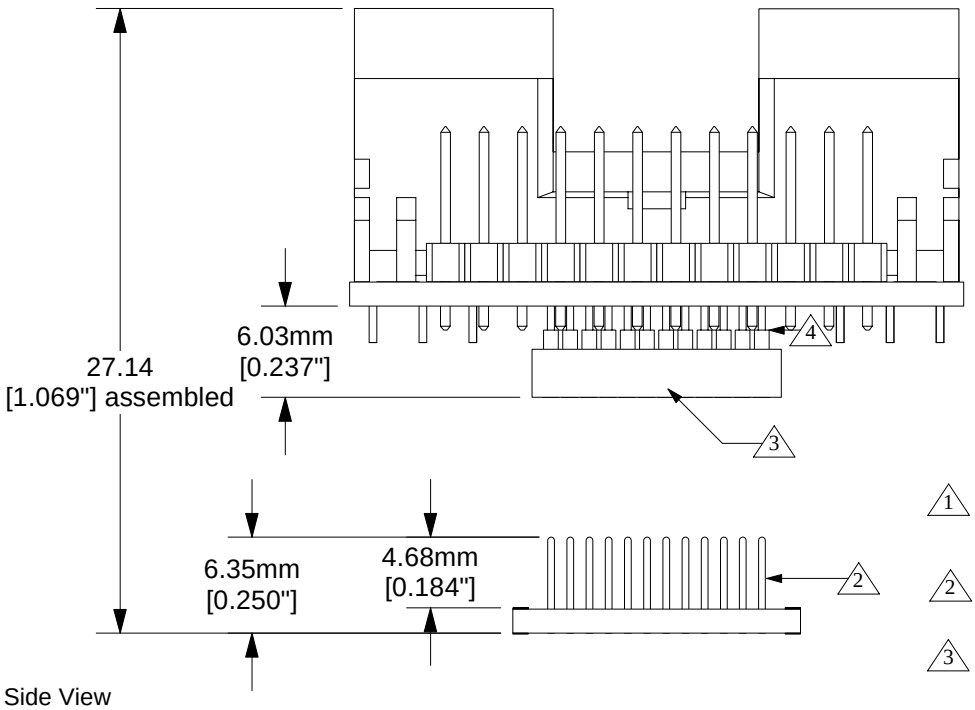


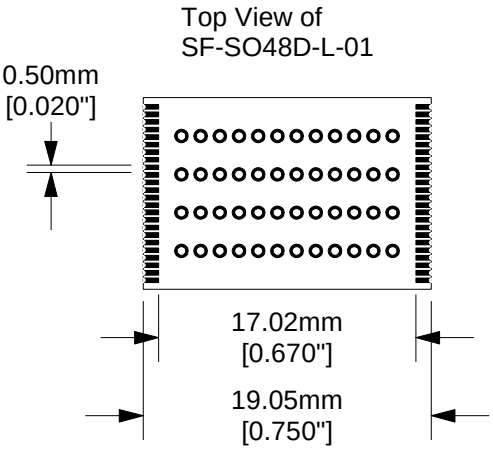


1. Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.
2. Substrate: 3.18mm ±0.18mm [0.125" ±0.007"] FR4/G10 or equivalent high temp material. Non-clad.
3. Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
4. Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.). Contact material- BeCu; finish 0.25µm [10µ"] Au over 2.54µm [100µ"] Ni (min. ).
5. Test points: material- Phosphor Bronze; plating- Sn over 1.27µm [50µ"] Ni. Gold flash on contact end.

Description: TSOP (Type I) Carrier Adaptor

48 position 0.5 mm pitch TSOP open top ZIF socket to 48 position 0.5 mm pitch TSOP (Type I) emulator foot with 48 test points.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from tru e position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

| CA-SO48D-L-Z-T-01 Drawing | Status: Released | Scale: 2:1 | Rev: A |
|---|---|---|---|
| <br>PO BOX 21151 ST. PAUL, MN 55121<br>Tele: (651) 452-8100<br>www.ironwoodelectronics.com | Drawing: E Smolentseva | Date: 8/14/01 | |
| | File: CA-SO48D-L-Z-T-01 Dwg.mcd | Modified: | |